

# Switch-mode Power Rectifier

## DPAK Surface Mount Package

# MURD330T4G, SURD8330T4G, SURD8330T4G-VF01

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

### Features

- Low Forward Voltage Drop
- Low Leakage
- Ultra-Fast Recovery Time
- SURD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Rated Reverse Voltage	$V_R$	300	V
Average Rectified Forward Current ( $T_C = 170^\circ\text{C}$ )	$I_F$	3.0	A
Non-Repetitive Peak Surge Current	$I_{FSM}$	75	A
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

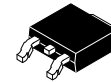


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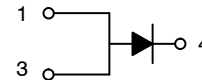
[www.onsemi.com](http://www.onsemi.com)

## ULTRAFAST RECTIFIER

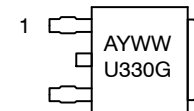
### 3 A, 300 V



DPAK  
CASE 369C



### MARKING DIAGRAM



U330 = Specific Device Code  
A = Assembly Location\*  
Y = Year  
WW = Work Week  
G = Pb-Free Package

\* The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

### ORDERING INFORMATION

Device	Package	Shipping†
MURD330T4G	DPAK (Pb-Free)	2,500/Tape & Reel
SURD8330T4G	DPAK (Pb-Free)	2,500/Tape & Reel
SURD8330T4G-VF01	DPAK (Pb-Free)	2,500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MURD330T4G, SURD8330T4G, SURD8330T4G-VF01

## THERMAL CHARACTERISTICS

Characteristics	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{\theta JC}$	2	$^{\circ}\text{C}/\text{W}$
Thermal Resistance – Junction-to-Ambient (Note 1)	$R_{\theta JA}$	49	$^{\circ}\text{C}/\text{W}$

1. Rating applies when surface mounted on a 700 mm<sup>2</sup>, 1 oz Cu heat spreader.

## ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage Drop ( $I_F = 3 \text{ A}$ , $T_J = 25^{\circ}\text{C}$ ) ( $I_F = 3 \text{ A}$ , $T_J = 150^{\circ}\text{C}$ )	$V_F$	1.15 0.92	V
Maximum Instantaneous Reverse Current ( $T_J = 25^{\circ}\text{C}$ , 300 V) ( $T_J = 150^{\circ}\text{C}$ , 300 V)	$I_R$	5 500	$\mu\text{A}$
Maximum Reverse Recovery Time ( $I_F = 1 \text{ A}$ , $di/dt = 50 \text{ A}/\mu\text{s}$ , $V_R = 30 \text{ V}$ , $T_J = 25^{\circ}\text{C}$ )	$t_{rr}$	50	ns
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V
Typical Peak Reverse Recovery Current ( $I_F = 1.0 \text{ A}$ , $di/dt = 50 \text{ A}/\mu\text{s}$ )	$I_{RM}$	1.5	A

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## TYPICAL CHARACTERISTICS

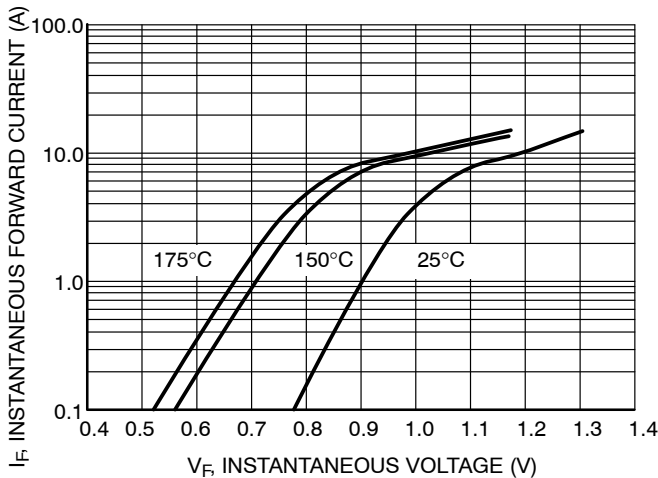


Figure 1. Typical Forward Voltage

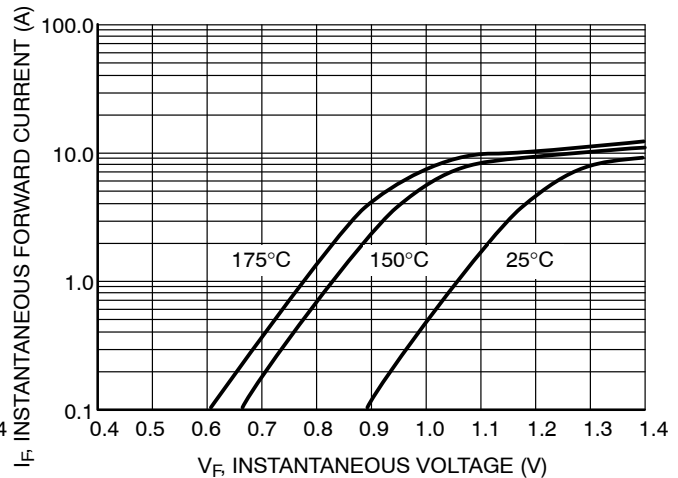


Figure 2. Maximum Forward Voltage

TYPICAL CHARACTERISTICS

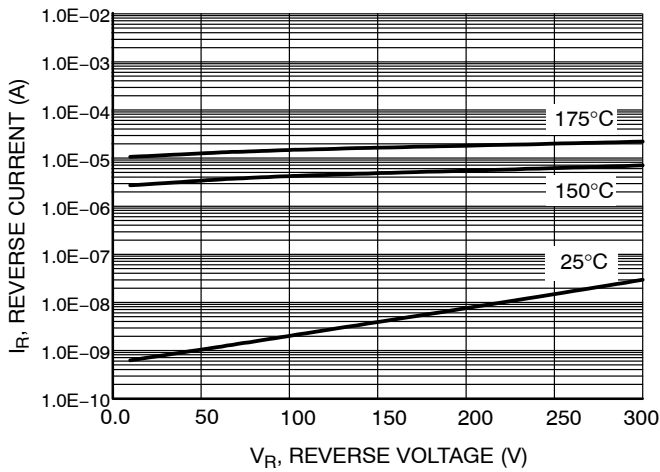


Figure 3. Typical Reverse Voltage

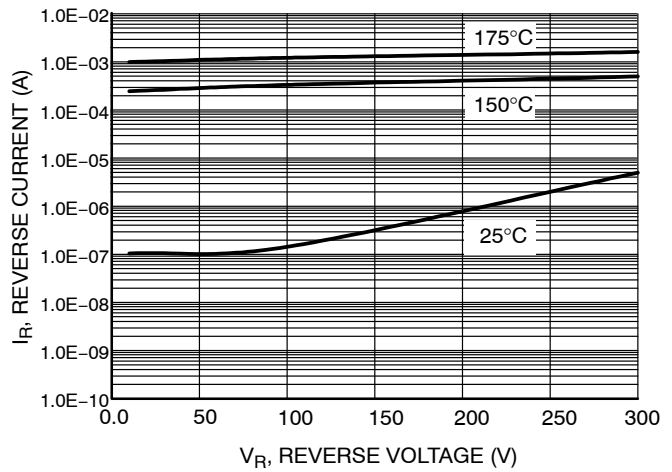


Figure 4. Maximum Reverse Voltage

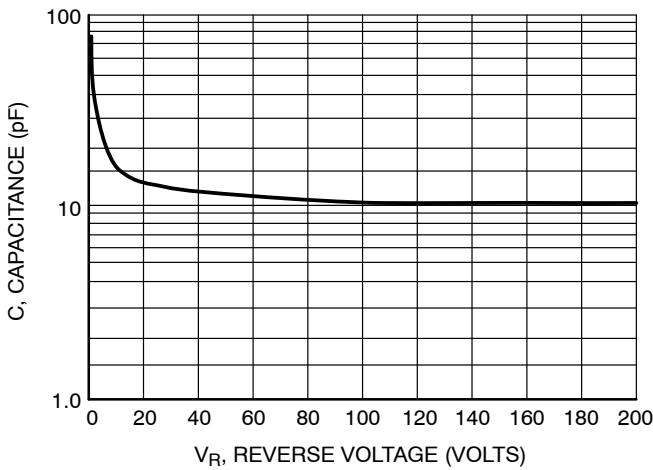


Figure 5. Typical Capacitance

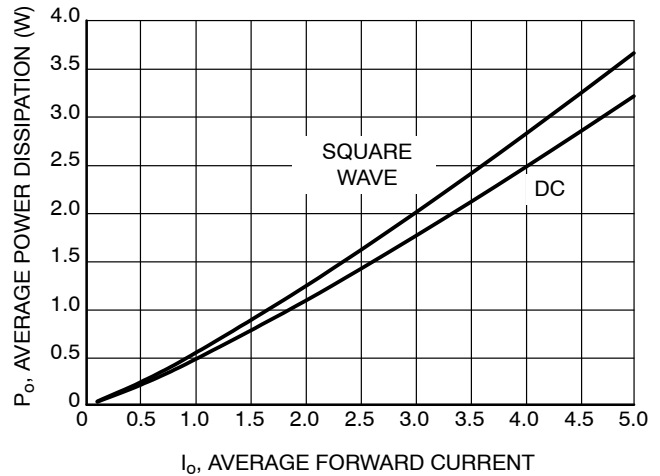


Figure 6. Power Dissipation

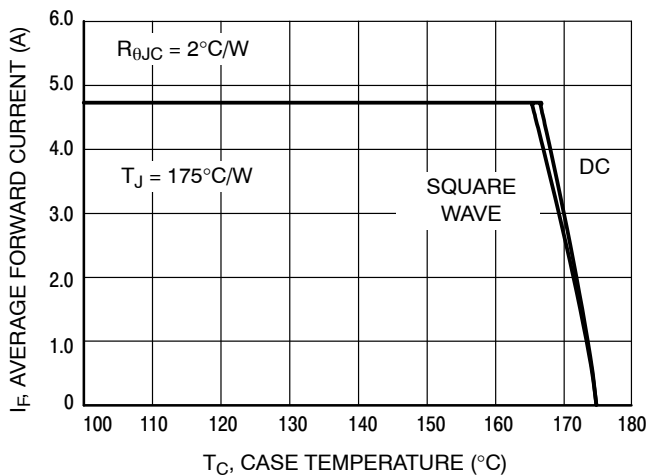


Figure 7. Current Derating, Case

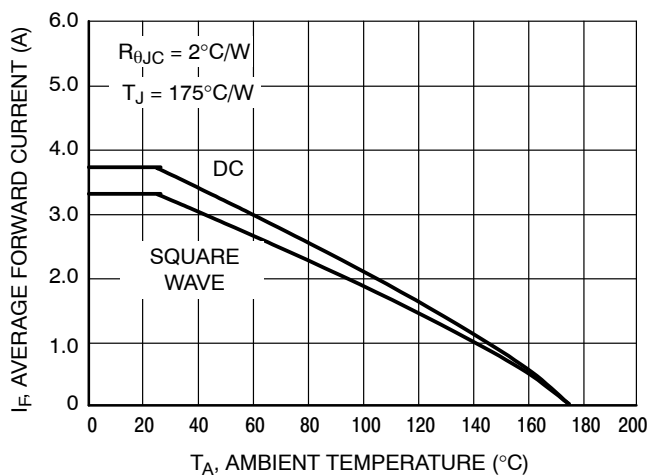
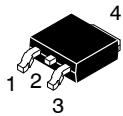


Figure 8. Current Derating, Ambient

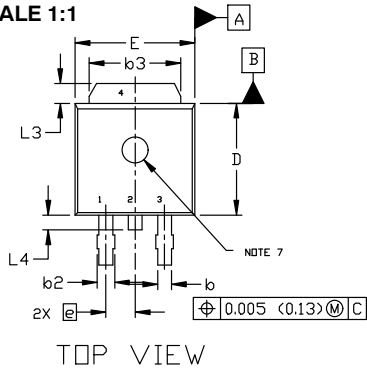
# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



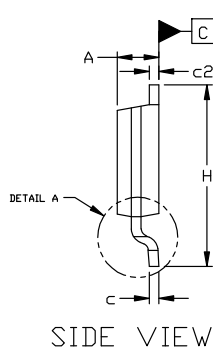
## DPAK (SINGLE GAUGE) CASE 369C ISSUE G

DATE 31 MAY 2023

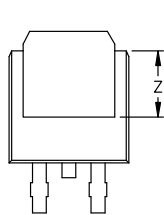
SCALE 1:1



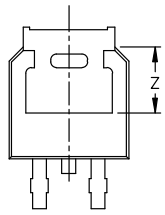
TOP VIEW



SIDE VIEW

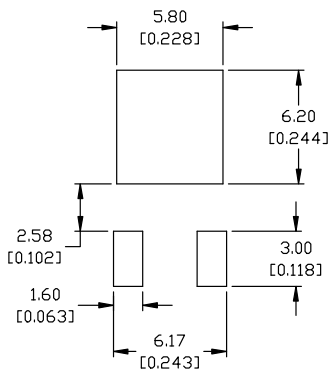


BOTTOM VIEW



BOTTOM VIEW

ALTERNATE CONSTRUCTIONS



### RECOMMENDED MOUNTING FOOTPRINT\*

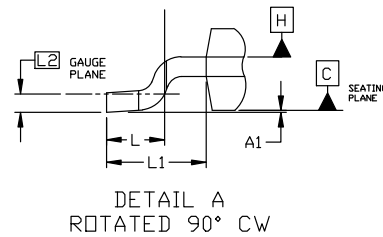
\*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

- |                                                                              |                                                                              |                                                                         |                                                                                   |                                                                          |
|------------------------------------------------------------------------------|------------------------------------------------------------------------------|-------------------------------------------------------------------------|-----------------------------------------------------------------------------------|--------------------------------------------------------------------------|
| <b>STYLE 1:</b><br>PIN 1. BASE<br>2. COLLECTOR<br>3. EMITTER<br>4. COLLECTOR | <b>STYLE 2:</b><br>PIN 1. GATE<br>2. DRAIN<br>3. SOURCE<br>4. DRAIN          | <b>STYLE 3:</b><br>PIN 1. ANODE<br>2. CATHODE<br>3. ANODE<br>4. CATHODE | <b>STYLE 4:</b><br>PIN 1. CATHODE<br>2. ANODE<br>3. GATE<br>4. ANODE              | <b>STYLE 5:</b><br>PIN 1. GATE<br>2. ANODE<br>3. CATHODE<br>4. ANODE     |
| <b>STYLE 6:</b><br>PIN 1. MT1<br>2. MT2<br>3. GATE<br>4. MT2                 | <b>STYLE 7:</b><br>PIN 1. GATE<br>2. COLLECTOR<br>3. EMITTER<br>4. COLLECTOR | <b>STYLE 8:</b><br>PIN 1. N/C<br>2. CATHODE<br>3. ANODE<br>4. CATHODE   | <b>STYLE 9:</b><br>PIN 1. ANODE<br>2. CATHODE<br>3. RESISTOR ADJUST<br>4. CATHODE | <b>STYLE 10:</b><br>PIN 1. CATHODE<br>2. ANODE<br>3. CATHODE<br>4. ANODE |

### NOTES:

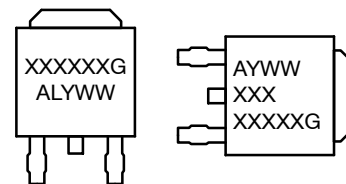
- DIMENSIONING AND TOLERANCING ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCHES
- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
- OPTIONAL MOLD FEATURE.

DIM	INCHES		MILLIMETERS	
	MIN.	MAX.	MIN.	MAX.
A	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
c	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
e	0.090	BSC	2.29	BSC
H	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114	REF	2.90	REF
L2	0.020	BSC	0.51	BSC
L3	0.035	0.050	0.89	1.27
L4	----	0.040	---	1.01
Z	0.155	----	3.93	---



DETAIL A  
ROTATED 90° CW

### GENERIC MARKING DIAGRAM\*



- IC**  
 XXXXXX = Device Code  
 A = Assembly Location  
 L = Wafer Lot  
 Y = Year  
 WW = Work Week  
 G = Pb-Free Package
- Discrete**  
 AYWW  
 XXX  
 XXXXXG

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<b>DESCRIPTION:</b>	<b>DPAK (SINGLE GAUGE)</b>	<b>PAGE 1 OF 1</b>

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